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Page : 2

Attorney's Docket No.: 14219-081US1
Client's Ref.: P2002,0957USN

AMENDMENTS TO THE SPECIFICATION:

Please amend the title on page 1, line 1, as follows:

~~Hermetically Encapsulated Component And Wafer-scale~~ Method For The Production
Thereof

Please add the following centered heading at page 1, line 3:

TECHNICAL FIELD

Please add the following centered heading at page 1, line 7:

BACKGROUND

Please add the following centered heading at page 5, line 7:

SUMMARY

Please add the following centered heading at page 10, line 20:

DESCRIPTION OF THE DRAWINGS

Please add the following centered heading at page 11, line 14:

DETAILED DESCRIPTION

Please amend the paragraph on page 12, lines 12 and 13, as follows:

The chip comprises, for example, ~~of~~ a semiconductor material such as Si, SiGe, or a III/V connection semiconductor such as GaAs, InP, InSb, etc.

Please replace the Abstract on page 34 with the following new Abstract:

A component includes a chip having a first chip face and a second chip face, where the first chip face includes component structures and connector metallizations associated with the component structures. The component also includes a frame structure on the first chip face and adjacent to the component structures, and a cover over the frame structure. The cover has a first cover face and a second cover face. The first cover face is closer to the chip than the second cover face. A back metallization is on the second chip face, on sides of the frame structure, and on sides of the cover. A contact is on the second cover face. There is a connection through the cover, which electrically connects the component structures and the contact. The connection is metallized and sealed.

Please delete the phrase "Figure 1" at page 34, line 14.